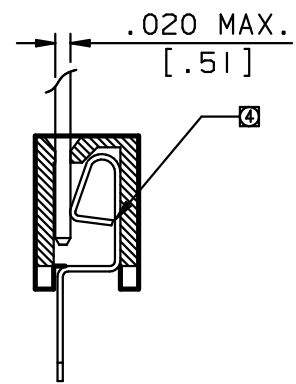
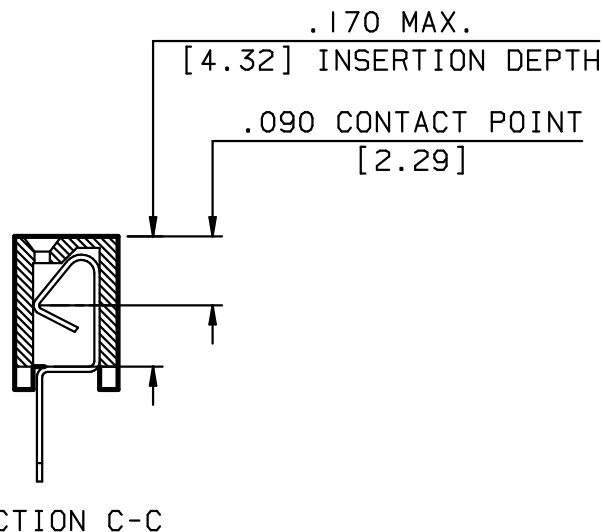
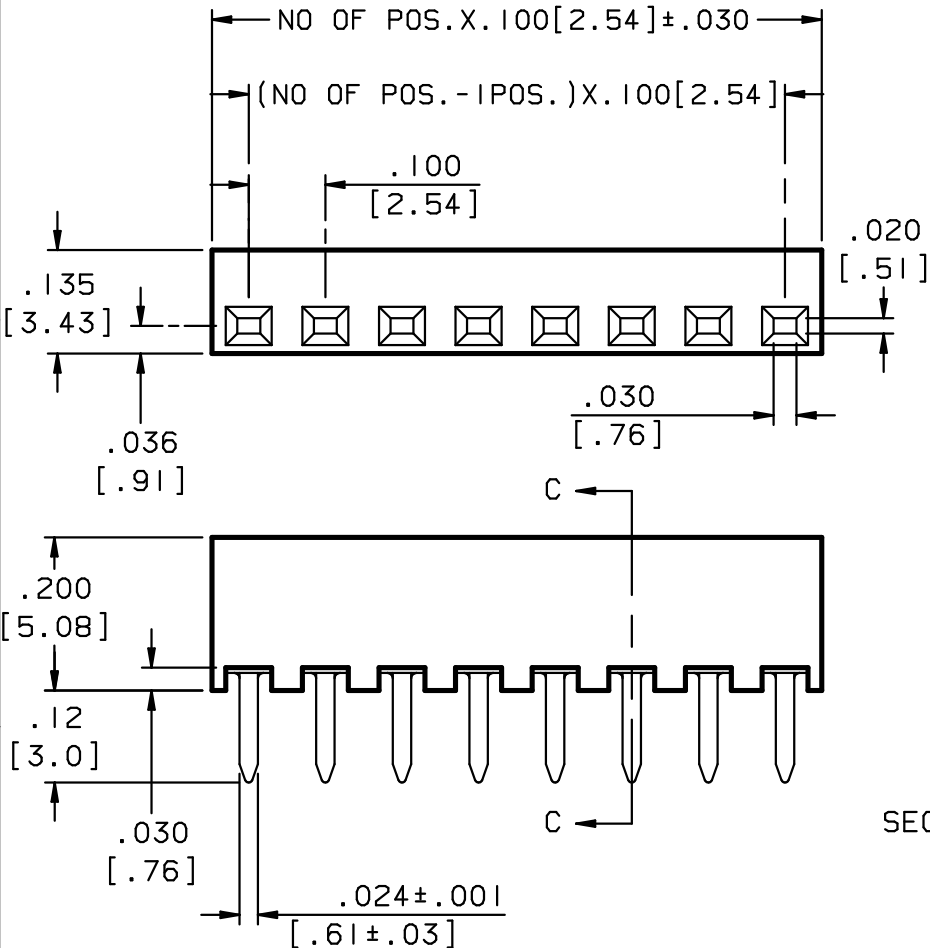


PART NO. CA-SXXSLP-T-SD

REVISIONS			
LTR	DESCRIPTION	DATE	APPROVED
D	ECO 199	6/23/81	
E	REDRAWN ECO 712	MDR 4/10/85	J.M. 4/10/85
F	SEE DO 6879	C.P. 08/28/09	A. J.
G	SEE DO 7613	C.P. 04/26/21	T.L.



CA-S XX SLP-T-SD

SINGLE ROW

NO. OF CONTACTS

SOCKET LOW PROFILE

PLATING:

-T = .000150 [0.00381025] TIN OVER
.000075 [0.002] NICKEL

CONTACT TYPE:

SD = SOLDER DIP

5. MEETS THE REQUIREMENTS OF THE EUROPEAN PARLIAMENT AND THE RESTRICTION OF THE USE OF CERTAIN HAZARDOUS SUBSTANCES IN ELECTRICAL AND ELECTRONIC EQUIPMENT. (RoHS)

- ④ OVER STRESS PROTECTION FEATURE.
- 3. CA-S08SLP-XX-SD SHOWN FOR ILLUSTRATION ONLY.
- 2. CONTACT MATERIAL: BERYLLIUM COPPER
- 1. INSULATOR MATERIAL: GLASS FILLED POLYESTER, BLACK, UL94V-0

NOTES: UNLESS OTHERWISE SPECIFIED

DIMENSIONS ARE IN INCHES TOLERANCES ARE:	APPROVALS	DATE	CIRCUIT ASSEMBLY CORP. 6 AUTRY SUITE 150, IRVINE, CALIFORNIA 92618
	DRAWN TAN MORRELL	03/01/85	
DECIMALS .XX ± .010 .XXX ± .005	CHECKED ART JOCHEN	04/10/85	CONNECTOR ASSEMBLY-SLP SERIES SINGLE INLINE, LOW PROFILE TYPE: SXXSLP, "RoHS"
DIMENSIONS IN BRACKETS () ARE IN MILLIMETERS TOLERANCES ARE:	THE INFORMATION AND DESIGN DISCLOSED HEREIN WAS OBTAINED BY AND IS THE PROPERTY OF CIRCUIT ASSEMBLY CORPORATION. CIRCUIT ASSEMBLY CORPORATION RESERVES ALL PATENT, PROPRIETARY, DESIGN, MANUFACTURING, REPRODUCTION, USE AND SALES RIGHTS THEREIN. AND TO ANY ARTICLE DISCLOSED HEREIN EXCEPT TO THE EXTENT RIGHTS ARE EXPRESSLY GRANTED TO OTHERS, THE FOREGOING DOES NOT APPLY TO VENDOR PROPRIETARY RIGHTS.		
DECIMALS .X ± .25 .XX ± .15	DO NOT SCALE DRAWING	SIZE C	CODE IDENT NO. 52072
		DRAWING NO. 610003	REV. G
		SCALE: 8:1	SHEET 1 OF 1